

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JUN CHUL KIM	02/07/2017
DONG SU KIM	02/07/2017
JONG MIN YOOK	02/07/2017
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<b>Postal Code:</b>	13509
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15441188
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<b>DATE SIGNED:</b>	02/23/2017
<b>Total Attachments: 1</b>	
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# ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) KIM, Jun Chul
- 2) KIM, Dong Su
- 3) YOOK, Jong Min
- 4)
- 5)  x box if continued on page 2

who has made a certain new and useful invention, hereby sells, assigns and transfers unto KOREA ELECTRONICS TECHNOLOGY INSTITUTE having a place of business at (Yatap-dong) 25, Saenari-ro, Bundang-gu, Seongnam-si, Gyeonggi-do, 13509, Republic of Korea, its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled:

### TITLE OF INVENTION


SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME

- (a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Patent Application No. \_\_\_\_\_; or
- (b) for which an application for United States Letters Patent was executed on \_\_\_\_\_.

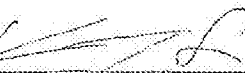
and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1)   
Name: KIM, Jun Chul

09/02/2019  
Date

2)   
Name: KIM, Dong Su

09/02/2019  
Date

3)   
Name: YOOK, Jong Min

09/02/2019  
Date

PATENT